

L Number	Hits	Search Text	DB	Time stamp
1	44	(US-5694740-\$ or US-5644169-\$ or US-5615052-\$ or US-5600541-\$ or US-5610431-\$ or US-5579207-\$ or US-5532513-\$ or US-5549870-\$ or US-5222014-\$ or US-5247423-\$ or US-5430421-\$ or US-4965660-\$ or US-4729010-\$ or US-6262362-\$ or US-6064126-\$ or US-5880403-\$ or US-5821762-\$ or US-6369448-\$ or US-6342406-\$ or US-6313522-\$ or US-6323550-\$ or US-6340894-\$ or US-6274929-\$ or US-6297072-\$ or US-6225692-\$ or US-6274927-\$).did. or (US-6185180-\$ or US-6188127-\$ or US-6143588-\$ or US-6214644-\$ or US-6163061-\$ or US-6025767-\$ or US-6140144-\$ or US-6117705-\$ or US-6101100-\$ or US-5962810-\$ or US-6025648-\$ or US-5936843-\$ or US-5790384-\$ or US-5866953-\$ or US-5783870-\$ or US-5730922-\$).did. or (US-20010008794-\$ or US-20010026010-\$).did.	USPAT; US-PGPUB	2002/07/17 15:11
2	17	("4801998"   "5222014"   "5231036"   "5578525"   "5579207"   "5786589"   "5821532"   "5867368"   "5907151"   "5962810"   "5973337"   "6046070"   "6122009"   "6143981"   "6144507"   "6247229"   "6281568").PN.	USPAT	2002/07/17 15:30
3	16	("5012323"   "5121293"   "5128831"   "5189505"   "5289337"   "5291061"   "5323060"   "5385869"   "5422435"   "5434745"   "5474957"   "5495398"   "5513076"   "5607099"   "5963430"   "6020629").PN.	USPAT	2002/07/17 15:33
4	2	6313522.URPN.	USPAT	2002/07/17 15:34
5	9	("4769344"   "5296408"   "5317922"   "5335550"   "5430421"   "5602385"   "5610431"   "5929728"   "6124145").PN.	USPAT	2002/07/17 15:35
6	0	6297072.URPN.	USPAT	2002/07/17 15:36
7	26	("3179913"   "3370203"   "3459998"   "3904934"   "4288841"   "4502098"   "4574331"   "4646128"   "4727410"   "4823233"   "4833568"   "4862249"   "4868712"   "4953005"   "5016138"   "5019945"   "5674785"   "5854507"   "5883426"   "5973392"   "6013948"   "6020629"   "6025648"   "6072233"   "6137164"   "6188127").PN.	USPAT	2002/07/17 15:37
11	4	("5610431"   "5719069"   "5915168"   "6074891").PN.	USPAT	2002/07/17 15:39
12	0	6214644.URPN.	USPAT	2002/07/17 15:40
13	4	6025767.URPN.	USPAT	2002/07/17 15:41
14	20	("0557132"   "3244947"   "3259814"   "3274458"   "3316465"   "3489965"   "3916080"   "3959577"   "3993123"   "4168480"   "4257905"   "4449580"   "4511873"   "4563697"   "4565901"   "4897508"   "5046161"   "5325265"   "5475280"   "5627396").PN.	USPAT	2002/07/17 15:42
21	8	5610431.URPN.	USPAT	2002/07/17 15:44
22	0	6373130.URPN.	USPAT	2002/07/17 15:46

23	2	("5578869"   "5610431").PN.	USPAT	2002/07/17 15:46
24	28	("4548078"   "4680606"   "4744249"   "4744863"   "4764244"   "4853669"   "4855544"   "4861420"   "4874499"   "4904978"   "4996082"   "4996627"   "5013396"   "5075253"   "5101669"   "5165289"   "5207103"   "5233871"   "5233874"   "5264075"   "5295395"   "5296408"   "5318652"   "5323051"   "5324683"   "5326726"   "5335544"   "5343064").PN.	USPAT	2002/07/17 15:47
-	162	(micromachine microelectronic) and ((lid cap) with (spacer bead))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/25 07:09
-	149	((micromachine microelectronic) and ((lid cap) with (spacer bead))) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT	2001/11/27 08:01
-	9	((micromachine microelectronic) and ((lid cap) with (spacer bead))) and substrate) and ((bond bonding) adj pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2001/11/26 09:27
-	140	((micromachine microelectronic) and ((lid cap) with (spacer bead))) and substrate) not (((micromachine microelectronic) and ((lid cap) with (spacer bead))) and substrate) and ((bond bonding) adj pad))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2001/11/26 10:11
-	7	((micromachine microelectronic) and ((lid cap) with (spacer bead))) and substrate) not (((micromachine microelectronic) and ((lid cap) with (spacer bead))) and substrate) and ((bond bonding) adj pad))) and package	USPAT; US-PGPUB; EPO; JPO; DERWENT	2001/11/26 10:25
-	0	5397897.pn. and micromachine	USPAT; US-PGPUB; EPO; JPO; DERWENT	2001/11/26 10:26
-	0	5397897.pn. and microelectronic	USPAT; US-PGPUB; EPO; JPO; DERWENT	2001/11/26 10:27
-	3	(micromachine microelectronic) and ((lid cap) with dam)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2001/11/26 10:47
-	116	257/619	USPAT; US-PGPUB; EPO; JPO; DERWENT	2001/11/26 13:58
-	516	257/620	USPAT; US-PGPUB; EPO; JPO; DERWENT	2001/11/26 13:58
-	410	257/621	USPAT; US-PGPUB; EPO; JPO; DERWENT	2001/11/26 13:58
-	1006	257/619 257/620 257/621	USPAT; US-PGPUB; EPO; JPO; DERWENT	2001/11/26 13:59
-	89	(257/619 257/620 257/621) and (lid cap cover) and ((bond bonding)adj pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2001/11/26 14:03

-	396	((micromachine micromachined microelectronic) near1 (device package)) and (lid cap) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT	2001/11/27 08:04
-	41	((micromachine micromachined) near1 (device package)) and (lid cap) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT	2001/11/27 08:04
-	10941	silicon near2 ceramic	USPAT; US-PGPUB; EPO; JPO; DERWENT	2001/11/27 14:06
-	2701	(silicon near2 ceramic) and (cap lid cover)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2001/11/27 14:07
-	134	silicon near2 ceramic) with(cap lid cover	USPAT; US-PGPUB; EPO; JPO; DERWENT	2001/11/27 14:07
-	53	((silicon near2 ceramic) with(cap lid cover)) and (semiconductor micromachined micromachine)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2001/11/27 14:08
-	51909	(micromachine micromechanical micromirror microelectronic)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/25 07:10
-	54209	(micromachine micromachined micromechanical micromirror microelectronic)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/04/12 07:18
-	165	((micromachine micromachined micromechanical micromirror microelectronic) ) and ((block blocking) near (adhesive material))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/25 07:19
-	2	"6274927"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/25 08:10
-	8	"5962810"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/25 07:19
-	9	"6274927" "5962810"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/25 07:19
-	5	5962810.URPN.	USPAT	2002/03/25 07:23
-	19	("4530152"   "4649418"   "4691225"   "4801998"   "4814943"   "4890383"   "5043004"   "5068713"   "5102829"   "5126818"   "5192681"   "5241133"   "5250470"   "5336931"   "5428188"   "5436203"   "5474957"   "5578525"   "5593926").PN.	USPAT	2002/03/25 07:24
-	23	("4530152"   "4649418"   "4691225"   "4801998"   "4890383"   "5043004"   "5102829"   "5126818"   "5192681"   "5241133"   "5250470"   "5336931"   "5436203"   "5474957"   "5530278"   "5578525"   "5593926"   "5612513"   "5776798"   "5861680"   "5866953"   "5893723"   "5918113").PN.	USPAT	2002/03/25 07:26
-	0	6274927.URPN.	USPAT	2002/03/25 07:29

-	38	("3838984"   "4691225"   "4801998"   "5057905"   "5070041"   "5117279"   "5122862"   "5159432"   "5230759"   "5256901"   "5258094"   "5336931"   "5435057"   "5436203"   "5497032"   "5529959"   "5644169"   "5656857"   "5776798"   "5859471"   "5861680"   "5866953"   "5867368"   "5877043"   "5877546"   "5893723"   "5895222"   "5905301"   "5949655"   "5950074"   "5962810"   "5972738"   "5981314"   "5989941"   "5998862"   "6034429"   "6092281"   "6117705").PN.	USPAT	2002/03/25 07:29
-	7683	(micromachine micromachined micromechanical (micromirror adj device))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/25 08:00
-	1427	((micromachine micromachined micromechanical (micromirror adj device)) ) and substrate and (wire wiring)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/25 07:40
-	661	((micromachine micromachined micromechanical (micromirror adj device)) ) and substrate and (wire wiring)) and (adhesive (sealing adj resin) encapsulant encapsulated encapsulation)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/25 07:45
-	655	((micromachine micromachined micromechanical (micromirror adj device)) ) and substrate and (wire wiring)) and (adhesive (sealing adj resin) encapsulant encapsulated encapsulation)) not ((micromachine micromachined micromechanical micromirror microelectronic) ) and ((block blocking) near (adhesive material)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/25 07:46
-	486	((micromachine micromachined micromechanical (micromirror adj device)) ) and substrate and (wire wiring)) and (adhesive (sealing adj resin) encapsulant encapsulated encapsulation)) not ((micromachine micromachined micromechanical micromirror microelectronic) ) and ((block blocking) near (adhesive material))) and wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/25 07:46
-	38	((micromachine micromachined micromechanical (micromirror adj device)) ) and substrate and (wire wiring)) and (adhesive (sealing adj resin) encapsulant encapsulated encapsulation)) not ((micromachine micromachined micromechanical micromirror microelectronic) ) and ((block blocking) near (adhesive material))) and wafer and curable	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/25 07:54
-	0	20020031847.URPN.	USPAT	2002/03/25 07:49
-	48	((micromachine micromachined micromechanical (micromirror adj device)) ) and substrate and (wire wiring)) and (adhesive (sealing adj resin) encapsulant encapsulated encapsulation)) not ((micromachine micromachined micromechanical micromirror microelectronic) ) and ((block blocking) near (adhesive material))) and curable	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/25 07:54

-	10	((((micromachine micromachined micromechanical (micromirror adj device)) ) and substrate and (wire wiring)) and (adhesive (sealing adj resin) encapsulant encapsulated encapsualation)) not ((micromachine micromachined micromechanical micromirror microelectronic) ) and ((block blocking) near (adhesive material)))) and curable) not ((((((micromachine micromachined micromechanical (micromirror adj device)) ) and substrate and (wire wiring)) and (adhesive (sealing adj resin) encapsulant encapsulated encapsualation)) not ((micromachine micromachined micromechanical micromirror microelectronic) ) and ((block blocking) near (adhesive material)))) and wafer) and curable)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/25 07:55
-	18	(micromachine micromachined micromechanical (micromirror adj device)) near3 (ccd (charge adj coupled adj device) (surface adj acoustical adj wave))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/25 08:05
-	0	6274927.pn. and curable	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/25 08:11
-	0	6143588.pn. and curable	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/25 08:12
-	0	6117705.pn. and curable	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/25 10:20
-	0	5866953.pn. and curable	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/25 08:16
-	3	5615052.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/25 08:16
-	2	6185180.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/25 08:16
-	5	6185180.pn. 5615052.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/25 08:16
-	2	6117705.pn. and ("300" "310" "320" "325" "329")	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/25 13:48
-	0	(hysol silicone) near3 stacky	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/25 14:07
-	377	(hysol silicone) near3 tacky	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/25 13:55
-	0	((hysol silicone) near3 tacky) with (gettering getter)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/25 13:51

-	0	((hysol silicone) near3 tacky) and (gettering getter)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/25 13:51
-	33	((hysol silicone) near3 tacky) and micro	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/25 13:54
-	86	((hysol silicone) near3 tacky) and (semiconductor IC electronic chip die)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/25 13:54
-	1	((hysol silicone) near3 tacky) and (semiconductor IC electronic chip die)) and hysol	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/25 13:55
-	1	adhesive near3 stacky	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/25 14:07
-	54209	micromachine micromachined micromechanical micromirror microelectronic	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/25 14:25
-	14411	(micromachine micromachined micromechanical micromirror microelectronic) and etching	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/25 14:26
-	1	(micromachine micromachined micromechanical micromirror microelectronic) and (etching near3 (active adj surface))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/25 14:29
-	1	(micromachine micromachined micromechanical micromirror microelectronic) and (etching near5 (active adj surface))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/25 14:30
-	19	(micromachine micromachined micromechanical micromirror microelectronic) and (etching with (active adj surface))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/25 14:34
-	82	(micromachine micromachined micromechanical micromirror microelectronic) and (etching with (resin adhesive encapsulant) with surface)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/25 14:36
-	81	((micromachine micromachined micromechanical micromirror microelectronic) and (etching with (resin adhesive encapsulant) with surface)) not ((micromachine micromachined micromechanical micromirror microelectronic) and (etching with (active adj surface)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/25 14:37
-	4678	(micromachine micromachined)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/04/12 07:00
-	346	((micromachine micromachined) ) and (cap lid) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/04/12 07:18
-	37	((micromachine micromachined) ) and (cap lid) and substrate) and (bump flipchip (flip adj chip) ((solder conductive metal) adj ball))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/04/12 07:19
-	7	("5369057"   "5585675"   "5663596"   "5721162"   "5831162"   "5907187"   "6087203").PN.	USPAT	2002/04/12 07:08
-	1	6225692.URPN.	USPAT	2002/04/12 07:09
-	4	("5610431"   "5719069"   "5915168"   "6074891").PN.	USPAT	2002/04/12 07:10

-	6	5610431.URPN.	USPAT	2002/04/12 07:11
-	0	6297072.URPN.	USPAT	2002/04/12 07:12
-	9	("4769344"   "5296408"   "5317922"   "5335550"   "5430421"   "5602385"   "5610431"   "5929728"   "6124145").PN.	USPAT	2002/04/12 07:12
-	28	("4548078"   "4680606"   "4744249"   "4744863"   "4764244"   "4853669"   "4855544"   "4861420"   "4874499"   "4904978"   "4996082"   "4996627"   "5013396"   "5075253"   "5101669"   "5165289"   "5207103"   "5233871"   "5233874"   "5264075"   "5295395"   "5296408"   "5318652"   "5323051"   "5324683"   "5326726"   "5335544"   "5343064").PN.	USPAT	2002/04/12 07:15
-	0	6214644.URPN.	USPAT	2002/04/12 07:17
-	54707	micromachine micromachined micromechanical micromirror microelectronic	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/04/12 07:18
-	252	((micromachine micromachined micromechanical micromirror microelectronic) and (cap lid) and substrate) and (flipchip (flip adj chip) ((solder conductive metal) adj (bum ball)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/04/12 07:34
-	234	((micromachine micromachined micromechanical micromirror microelectronic) and (cap lid) and substrate) and (flipchip (flip adj chip) ((solder conductive metal) adj (bum ball))) not (((micromachine micromachined) ) and (cap lid) and substrate) and (bump flipchip (flip adj chip) ((solder conductive metal) adj ball)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/04/12 07:20
-	0	((micromachine micromachined micromechanical micromirror microelectronic) and (cap lid) and substrate) and (flipchip (flip adj chip) ((solder conductive metal) adj (bum ball))) not (((micromachine micromachined) ) and (cap lid) and substrate) and (bump flipchip (flip adj chip) ((solder conductive metal) adj ball))) and ((electro magnetic) near2 shield)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/04/12 07:36
-	24	((micromachine micromachined micromechanical micromirror microelectronic) and (cap lid) and substrate) and (flipchip (flip adj chip) ((solder conductive metal) adj (bum ball))) not (((micromachine micromachined) ) and (cap lid) and substrate) and (bump flipchip (flip adj chip) ((solder conductive metal) adj ball))) and shield	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/04/12 07:36
-	240	(micromachine micromachined micromechanical micromirror microelectronic) and ((insulating insulative dielectric insulation) near3 (cap lid))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/04/12 07:27

-	240	((micromachine micromachined micromechanical micromirror microelectronic) and ((insulating insulative dielectric insulation) near3 (cap lid))) not (((micromachine micromachined) ) and (cap lid) and substrate) and (bump flipchip (flip adj chip) ((solder conductive metal) adj ball)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/04/12 07:27
-	1	((micromachine micromachined micromechanical micromirror microelectronic) and ((insulating insulative dielectric insulation) near3 (cap lid))) not (((micromachine micromachined) ) and (cap lid) and substrate) and (bump flipchip (flip adj chip) ((solder conductive metal) adj ball))) and ((cap lid) near3 ((bond bonding metal conductive) near pad))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/04/12 07:30
-	2	((micromachine micromachined micromechanical micromirror microelectronic) and ((insulating insulative dielectric insulation) near3 (cap lid))) not (((micromachine micromachined) ) and (cap lid) and substrate) and (bump flipchip (flip adj chip) ((solder conductive metal) adj ball))) and ((cap lid) with ((bond bonding metal conductive) near pad))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/04/12 07:29
-	16	((micromachine micromachined micromechanical micromirror microelectronic) and ((insulating insulative dielectric insulation) near3 (cap lid))) not (((micromachine micromachined) ) and (cap lid) and substrate) and (bump flipchip (flip adj chip) ((solder conductive metal) adj ball))) and ((bond bonding metal conductive) near pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/04/12 07:36
-	30962	semiconductor near2 (package packaging)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/04/12 07:33
-	3754	(semiconductor near2 (package packaging)) and (flipchip (flip adj chip) ((solder conductive metal) adj (bum ball)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/04/12 07:34
-	1615	((semiconductor near2 (package packaging)) and (flipchip (flip adj chip) ((solder conductive metal) adj (bum ball)))) and (cap lid cover) and (base substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/04/12 07:42
-	930	((semiconductor near2 (package packaging)) and (flipchip (flip adj chip) ((solder conductive metal) adj (bum ball)))) and (cap lid cover) and (base substrate)) and ((bond bonding metal conductive) near pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/04/12 07:36
-	3	((semiconductor near2 (package packaging)) and (flipchip (flip adj chip) ((solder conductive metal) adj (bum ball)))) and (cap lid cover) and (base substrate)) and ((bond bonding metal conductive) near pad)) and ((electro magnetic) near2 shield)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/04/12 07:36
-	50	((semiconductor near2 (package packaging)) and (flipchip (flip adj chip) ((solder conductive metal) adj (bum ball)))) and (cap lid cover) and (base substrate)) and ((bond bonding metal conductive) near pad)) and shield	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/04/12 07:37



-	195	((semiconductor near2 (package packaging)) and (flipchip (flip adj chip) ((solder conductive metal) adj (bum ball)))) and ((cap lid cover) with ((through adj hole) vias)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/04/12 07:53
-	181	((semiconductor near2 (package packaging)) and (flipchip (flip adj chip) ((solder conductive metal) adj (bum ball)))) and ((cap lid cover) with ((through adj hole) vias))) not (((semiconductor near2 (package packaging)) and (flipchip (flip adj chip) ((solder conductive metal) adj (bum ball)))) and (cap lid cover) and (base substrate)) and ((bond bonding metal conductive) near pad)) and shield)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/04/12 07:43
-	376878	((semiconductor near2 (package packaging)) and (flipchip (flip adj chip) ((solder conductive metal) adj (bum ball)))) and ((cap lid cover) with ((through adj hole) vias))) not (((semiconductor near2 (package packaging)) and (flipchip (flip adj chip) ((solder conductive metal) adj (bum ball)))) and (cap lid cover) and (base substrate)) and ((bond bonding metal conductive) near pad)) and shield)) (stack stacked)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/04/12 07:43
-	44	((semiconductor near2 (package packaging)) and (flipchip (flip adj chip) ((solder conductive metal) adj (bum ball)))) and ((cap lid cover) with ((through adj hole) vias))) not (((semiconductor near2 (package packaging)) and (flipchip (flip adj chip) ((solder conductive metal) adj (bum ball)))) and (cap lid cover) and (base substrate)) and ((bond bonding metal conductive) near pad)) and shield)) and (stack stacked)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/04/12 07:55
-	1278	((semiconductor near2 (package packaging)) and (flipchip (flip adj chip) ((solder conductive metal) adj (bum ball)))) and ((cap lid cover) and((through adj hole) vias)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/04/12 07:54
-	1054	((semiconductor near2 (package packaging)) and (flipchip (flip adj chip) ((solder conductive metal) adj (bum ball)))) and ((cap lid cover) and((through adj hole) vias))) not (((semiconductor near2 (package packaging)) and (flipchip (flip adj chip) ((solder conductive metal) adj (bum ball)))) and (cap lid cover) and (base substrate)) and ((bond bonding metal conductive) near pad)) and shield) not ((semiconductor near2 (package packaging)) and (flipchip (flip adj chip) ((solder conductive metal) adj (bum ball)))) and ((cap lid cover) with ((through adj hole) vias)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/04/12 07:55

-	1191	((semiconductor near2 (package packaging)) and (flipchip (flip adj chip) ((solder conductive metal) adj (bum ball)))) and ((cap lid cover) and((through adj hole) vias))) not (((semiconductor near2 (package packaging)) and (flipchip (flip adj chip) ((solder conductive metal) adj (bum ball)))) and (cap lid cover) and (base substrate)) and ((bond bonding metal conductive) near pad)) and shield) not (((semiconductor near2 (package packaging)) and (flipchip (flip adj chip) ((solder conductive metal) adj (bum ball)))) and ((cap lid cover) with ((through adj hole) vias))) not (((semiconductor near2 (package packaging)) and (flipchip (flip adj chip) ((solder conductive metal) adj (bum ball)))) and (cap lid cover) and (base substrate)) and ((bond bonding metal conductive) near pad)) and shield)) and (stack stacked))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/04/12 07:55
-	0	6294406.URPN.	USPAT	2002/04/12 08:09
-	16	("4703483"   "5109320"   "5323060"   "5399898"   "5401672"   "5434453"   "5446247"   "5495394"   "5541449"   "5563773"   "5576519"   "5600541"   "5760478"   "5770480"   "5790384"   "6069025").PN.	USPAT	2002/04/12 08:09
-	20	5600541.URPN.	USPAT	2002/04/12 08:11
-	7	6025648.URPN.	USPAT	2002/04/12 08:15
-	8	("5276289"   "5798567"   "5854507"   "5869894"   "5936843"   "5969944"   "5994166"   "6025648").PN.	USPAT	2002/04/12 08:18
-	26	("3179913"   "3370203"   "3459998"   "3904934"   "4288841"   "4502098"   "4574331"   "4646128"   "4727410"   "4823233"   "4833568"   "4862249"   "4868712"   "4953005"   "5016138"   "5019945"   "5674785"   "5854507"   "5883426"   "5973392"   "6013948"   "6020629"   "6025648"   "6072233"   "6137164"   "6188127").PN.	USPAT	2002/04/12 08:22
-	16	("4894706"   "5016138"   "5222014"   "5247423"   "5600541"   "5633783"   "5715144"   "5742477"   "5760478"   "5786628"   "5798562"   "5801438"   "5807986"   "5811879"   "5838060"   "5838551").PN.	USPAT	2002/04/12 08:26
-	95	5222014.URPN.	USPAT	2002/04/12 08:30
-	24	5790384.URPN.	USPAT	2002/04/12 08:30
-	22	5783870.URPN.	USPAT	2002/04/12 09:10
-	36	("3436603"   "4807021"   "4867235"   "4933810"   "4953060"   "4991000"   "5060844"   "5099309"   "5128831"   "5130894"   "5172303"   "5222014"   "5241133"   "5241450"   "5241456"   "5247423"   "5299094"   "5307240"   "5313366"   "5376825"   "5391917"   "5394010"   "5394300"   "5397917"   "5412538"   "5421081"   "5422435"   "5454160"   "5579207"   "5615089"   "5633783"   "5642265"   "5739581"   "5783870"   "5798564"   "5920117").PN.	USPAT	2002/04/12 09:13

-	40	(US-6025767-\$ or US-6163061-\$ or US-6323550-\$ or US-6225692-\$ or US-6214644-\$ or US-5694740-\$ or US-6140144-\$ or US-5532513-\$ or US-4965660-\$ or US-4729010-\$ or US-6342406-\$ or US-6274927-\$ or US-6143588-\$ or US-5962810-\$ or US-5866953-\$ or US-6117705-\$ or US-5644169-\$ or US-6185180-\$ or US-5615052-\$ or US-5610431-\$ or US-5730922-\$ or US-5549870-\$ or US-6297072-\$ or US-5430421-\$ or US-6274929-\$ or US-6369448-\$).did. or (US-6340894-\$ or US-6313522-\$ or US-5790384-\$ or US-5600541-\$ or US-6025648-\$ or US-5936843-\$ or US-6188127-\$ or US-5247423-\$ or US-5222014-\$ or US-6101100-\$ or US-5783870-\$ or US-5579207-\$).did. or (US-20010026010-\$ or US-20010008794-\$).did.	USPAT; US-PGPUB	2002/04/15 09:08
-	3	((US-6025767-\$ or US-6163061-\$ or US-6323550-\$ or US-6225692-\$ or US-6214644-\$ or US-5694740-\$ or US-6140144-\$ or US-5532513-\$ or US-4965660-\$ or US-4729010-\$ or US-6342406-\$ or US-6274927-\$ or US-6143588-\$ or US-5962810-\$ or US-5866953-\$ or US-6117705-\$ or US-5644169-\$ or US-6185180-\$ or US-5615052-\$ or US-5610431-\$ or US-5730922-\$ or US-5549870-\$ or US-6297072-\$ or US-5430421-\$ or US-6274929-\$ or US-6369448-\$).did. or (US-6340894-\$ or US-6313522-\$ or US-5790384-\$ or US-5600541-\$ or US-6025648-\$ or US-5936843-\$ or US-6188127-\$ or US-5247423-\$ or US-5222014-\$ or US-6101100-\$ or US-5783870-\$ or US-5579207-\$).did. or (US-20010026010-\$ or US-20010008794-\$).did.) and (emi (electro nearl magnetic nearl shield))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/04/15 09:11
-	1	((US-6025767-\$ or US-6163061-\$ or US-6323550-\$ or US-6225692-\$ or US-6214644-\$ or US-5694740-\$ or US-6140144-\$ or US-5532513-\$ or US-4965660-\$ or US-4729010-\$ or US-6342406-\$ or US-6274927-\$ or US-6143588-\$ or US-5962810-\$ or US-5866953-\$ or US-6117705-\$ or US-5644169-\$ or US-6185180-\$ or US-5615052-\$ or US-5610431-\$ or US-5730922-\$ or US-5549870-\$ or US-6297072-\$ or US-5430421-\$ or US-6274929-\$ or US-6369448-\$).did. or (US-6340894-\$ or US-6313522-\$ or US-5790384-\$ or US-5600541-\$ or US-6025648-\$ or US-5936843-\$ or US-6188127-\$ or US-5247423-\$ or US-5222014-\$ or US-6101100-\$ or US-5783870-\$ or US-5579207-\$).did. or (US-20010026010-\$ or US-20010008794-\$).did.) and (emi (electromagnetic nearl shield))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/04/15 09:12

-	1	((US-6025767-\$ or US-6163061-\$ or US-6323550-\$ or US-6225692-\$ or US-6214644-\$ or US-5694740-\$ or US-6140144-\$ or US-5532513-\$ or US-4965660-\$ or US-4729010-\$ or US-6342406-\$ or US-6274927-\$ or US-6143588-\$ or US-5962810-\$ or US-5866953-\$ or US-6117705-\$ or US-5644169-\$ or US-6185180-\$ or US-5615052-\$ or US-5610431-\$ or US-5730922-\$ or US-5549870-\$ or US-6297072-\$ or US-5430421-\$ or US-6274929-\$ or US-6369448-\$).did. or (US-6340894-\$ or US-6313522-\$ or US-5790384-\$ or US-5600541-\$ or US-6025648-\$ or US-5936843-\$ or US-6188127-\$ or US-5247423-\$ or US-5222014-\$ or US-6101100-\$ or US-5783870-\$ or US-5579207-\$).did. or (US-20010026010-\$ or US-20010008794-\$).did.) and (emi (electromagnetic nearl interference))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/04/15 09:16
-	2191	(micromachine micromachined micromechanical micromirror microelectronic) and (cap lid) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/04/15 09:16
-	108	((micromachine micromachined micromechanical micromirror microelectronic) and (cap lid) and substrate) and (emi (electromagnetic nearl (shield interference)) (electro adj magnetic adj interference))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/04/15 09:18
-	64	((micromachine micromachined micromechanical micromirror microelectronic) and (cap lid) and substrate) and ((electromagnetic nearl (shield interference)) (electro adj magnetic adj interference))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/04/15 09:18
-	30	((micromachine micromachined micromechanical micromirror microelectronic) and (cap lid) and substrate) and (emi (electromagnetic nearl (shield interference)) (electro adj magnetic adj interference))) and (semiconductor nearl (device package packaging))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/04/15 09:41
-	10	5639989.pn. 5578525.pn. 5981314.pn. 6150716.pn. 6308938.pn	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/04/15 09:42